ANADIGICS

10GB/s Offset Control TIA

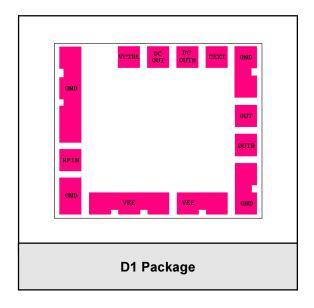
Advanced Product Information - Rev 0

FEATURES

- **Differential Output Topology**
- DC Output Offset Control (external loop)
- Low Group Delay
- DC Coupled Outputs
- -5.2V Power Supply
- InGaP HBT Technology

APPLICATIONS

- SONET OC-192/STM-64
- 10Gb/s DWDM
- 10Gb/s Datacom

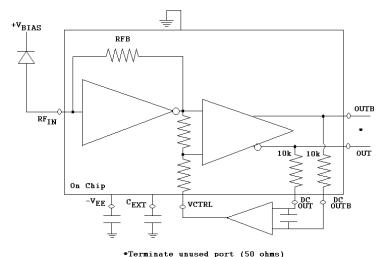


PRODUCT DESCRIPTION

device is used in conjunction with a photodetector to threshold for the post amplifier. convert an optical signal into a differential voltage

The ANADIGICS ATA7602 is a -5.2V high speed that can be AC or DC coupled to a post amplifier. transimpedance amplifier (TIA) for 10Gb/s The DC offset between the two outputs can be adjusted applications available in bare die form and in order to maintain low dury cycle distortion for large manufactured using an InGaP HBT process. The signal operation or to provide an adjustable decision

Figure 1: Block Diagram



Absolute Maximum Ratings

| PARAMETER | MIN | TYP | MAX | UNIT |
|-----------------------|------|-----|-----|------|
| DC Power supply (VEE) | -7.0 | | 1.0 | V |
| Storage Temperature | -65 | | 125 | °C |
| DC Input Current | | | 3.0 | mA |

Operating Conditions

| PARAMETER | MIN | TYP | MAX | UNIT |
|--------------------------------------|-------|------|-------|------|
| Operating Voltage Range | -5.50 | -5.2 | -4.90 | ٧ |
| Operating Temperature Range | -40 | | 85 | °C |
| Photodiode Capacitance (PIN + stray) | | | 0.3 | pF |
| Series Resistance (Bondwire + anode) | | | 15 | Ω |
| Bondwire Inductance | | | 1.0 | nΗ |

DC Characteristics

| PARAMETER | MIN | TYP | MAX | UNIT |
|-----------------------------|-----|------|-----|------|
| Supply Current (DC Coupled) | | 115 | 155 | mA |
| Input DC Voltage | | -3.9 | | V |
| Output DC Voltage | | -0.4 | | V |

AC Electrical Characteristics (VEE=-5.2V+/-0.3V, CDIODE+CSTRAY=0.3PF, LBOND=0.7nH)

| PARAMETER | MIN | TYP | MAX | UNIT |
|-----------------------------------------------------------------|------|------|-----|------|
| Small Signal Differential Transimpedance ($R_L = 100 \Omega$) | 2000 | 2200 | | Ω |
| Maximum Output Voltage Swing (R $_{\rm L}$ = 50 Ω) | 600 | 700 | 800 | m∨pp |
| Input Current @ 80% Output Saturation | 550 | | | μАрр |
| Bandwidth (-3dB; I _{input} <= 1.65mApk-pk) | 8.5 | 9.5 | | GHz |
| Low Frequency Cutoff ⁽¹⁾⁽⁴⁾ | | 30 | | kHz |
| Group Delay Deviation (30kHz to 8.0GHz) (1) | -15 | | +15 | ps |
| Group Delay Deviation (30kHz to Fc) (1) | -25 | | +25 | ps |
| Optical Sensitivity (with a PIN Photodiode) (2)(3)(4)(5) | | -19 | | dBm |
| Optical Overload (with a PIN Photodiode) (2)(3)(4) | 0 | | | dBm |
| Output Return Loss (10MHz to Fc) | | -15 | -12 | dB |
| Output Return Loss (F _c to 20GHz) | | | -5 | dB |

⁽¹⁾ Optical input power = -19 to 0dBm, $F_c = 9.5 GHz$

 ⁽²⁾ Responsivity of the photodiode = 0.95A/W typical, laser extinction ratio=10dB
 (3) BER: 10⁻¹⁰; 9.95328Gbps NRZ pattern; PRBS 2³¹-1, λ=1.55μm
 (4) External 1nF Capacitor Required (C_{ext}: see figure 3)
 (5) Measurements made in reference fixture with open cavity fiber alignment. Improvements in coupling will result in better performance.

Pad Description

| PAD | Description | Comment |
|-----------|--------------------------------------------------------------------------------|--------------------------------------------------------|
| VEE1, VEE | Negative Supply Voltage | -5.2V |
| RFIN | TIA Input | Connect to detector anode |
| DC OUT | Non-inverted DC Output Voltage | Feeds into External Op-amp for Offset control |
| DC OUTB | Inverted DC Output Voltage | Feeds into External Op-amp for Offset control |
| Vctrl | Offset Control | Use to set relative DC offset between the output ports |
| Сехт | Pad for bonding external capacitor to ground in order to set low freq. Cutoff) | Choose Capacitor using the attached chart |
| OUT | TIA Output Voltage (Non-inverted) | Logical '1' with optical input |
| OUTB | TIA Output Voltage (Inverted) | Logical '0' with optical input |

Figure 2: Die Size and layout

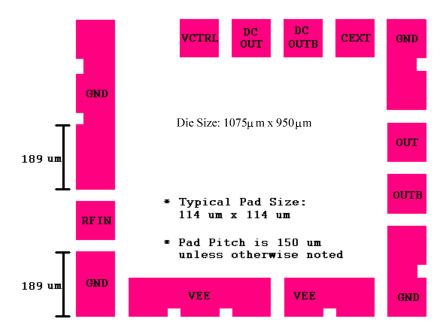


Figure 3: Calculated External Capacitor Size vs. Low Frequency Cutoff

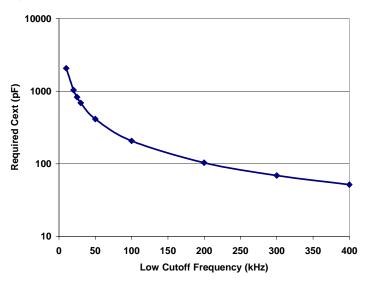


Figure 4: Simulated Bandwidth



Figure 5: Simulated Group Delay

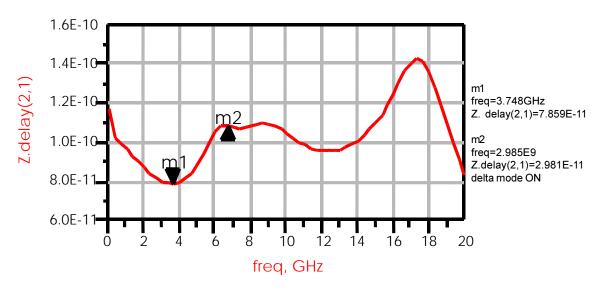


Figure 6: Simulated Bandwidth and Group Delay vs. Input Inductance

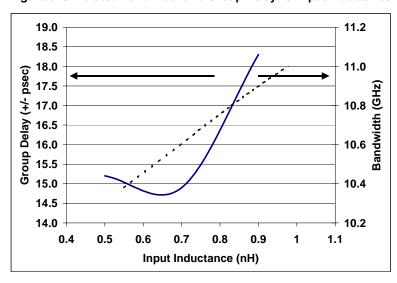


Figure 7: Simulated Output Return Loss



Ordering Information

| Part Number | Package Option | Package Description |
|-------------|----------------|---------------------|
| ATA7602D1 | D1 | Die |



ANADIGICS, Inc.
141 Mount Bethel Road

Warren, New Jersey 07059, U.S.A Tel: +1 (908) 668-5000

Fax: +1 (908) 668-5132 http://www.anadigics.com

Mktg@anadigics.com

IMPORTANT NOTICE

ANADIGICS, Inc. reserves the right to make changes to its products or discontinue any product at any time without notice. The Advanced Product data sheets and product specifications contained in this data sheet are subject to change prior to a products formal introduction. The information in this data sheet has been carefully checked and is assumed to be reliable. However, ANADIGICS assumes no responsibility for inaccuracies. ANADIGICS strongly urges customers to verify that the information they are using is current before placing orders.

WARNING

ANADIGICS products are not intended for use in life support appliances, devices, or systems. Use of an ANADIGICS product in any such application without written consent is prohibited.

